



512K X 8 BIT LOW POWER CMOS SRAM

FEATURES

- Access time : 55 ns
- Low power consumption:  
Operating current : 30/20mA (TYP.)  
Standby current : 4 μA (TYP.) C-version
- Single 2.7V ~ 5.5V power supply
- Fully Compatible with all Competitors 5V product
- Fully Compatible with all Competitors 3.3V product
  
- Fully static operation
- Tri-state output
- Data retention voltage : 2.0V (MIN.)
- All products ROHS Compliant
- Package 32-pin 450 mil SOP  
32-pin 8mm x 20mm TSOP-I  
32-pin 600 mil P-DIP  
32-pin 8mm x 13.4mm sTSOP  
\*36-ball 6mm x 8mm TFBGA  
\*44-pin 8mm x 20mm TSOP-II

Coming  
Soon!

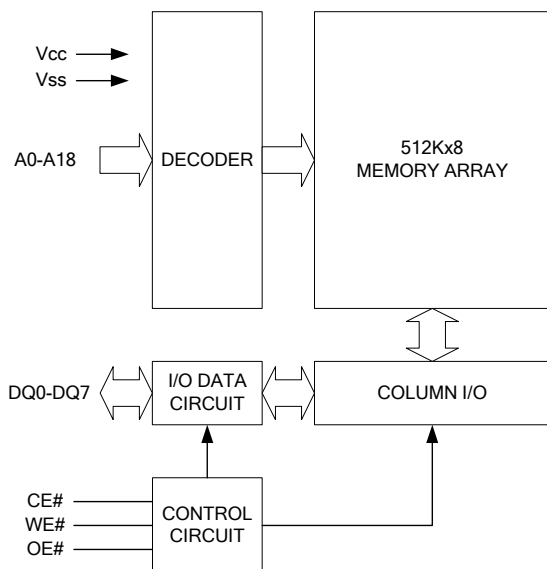
GENERAL DESCRIPTION

The AS6C4008 is a 4,194,304-bit low power CMOS static random access memory organized as 524,288 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

The AS6C4008 is well designed for very low power system applications, and particularly well suited for battery back-up non-volatile memory application.

The AS6C4008 operates from a single power supply of 2.7V ~ 5.5V

FUNCTIONAL BLOCK DIAGRAM



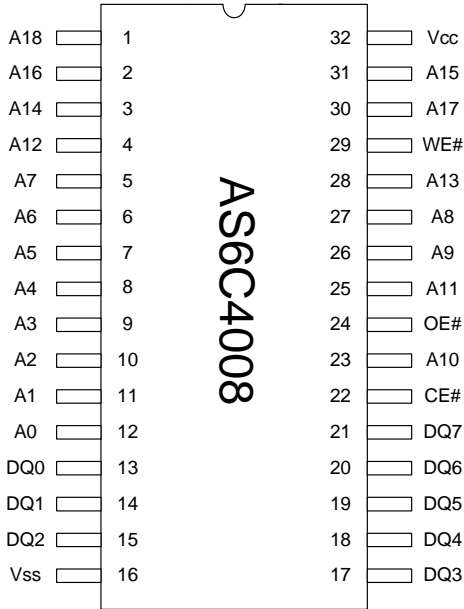
PIN DESCRIPTION\*\*

SYMBOL	DESCRIPTION
A0 - A18	Address Inputs
DQ0 - DQ7	Data Inputs/Outputs
CE#	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection

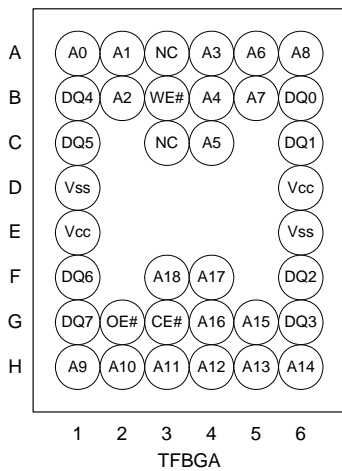


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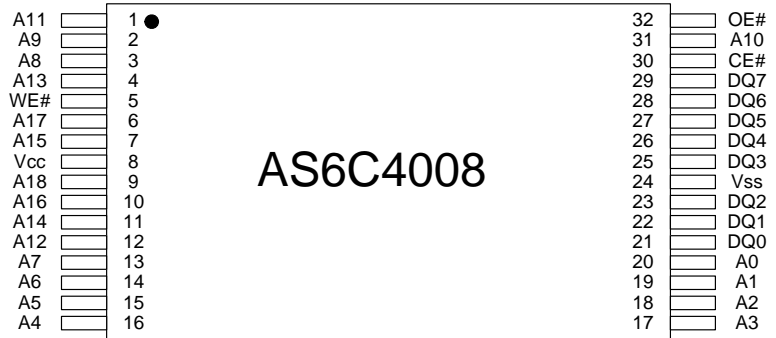
**PIN CONFIGURATION**



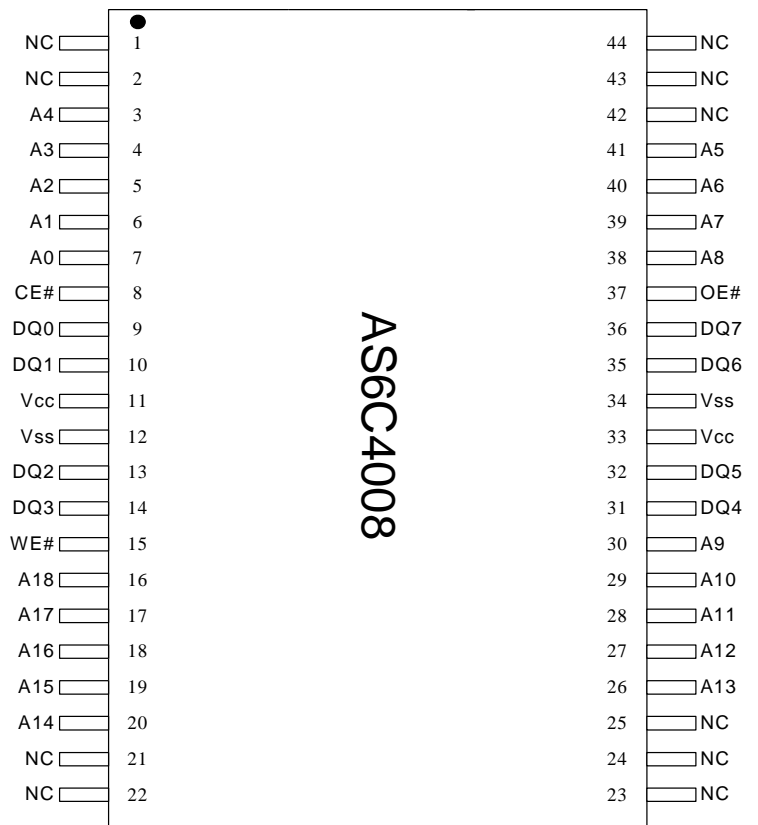
SOP/P-DIP



TFBGA



TSOP-I/sTOSOP



TSOP-II



## 512K X 8 BIT LOW POWER CMOS SRAM

**ABSOLUTE MAXIMUM RATINGS\***

PARAMETER	SYMBOL	RATING	UNIT
Terminal Voltage with Respect to V <sub>SS</sub>	V <sub>TERM</sub>	-0.5 to 6.5	V
Operating Temperature	T <sub>A</sub>	0 to 70(C grade)	°C
		-40 to 85(I grade)	
Storage Temperature	T <sub>STG</sub>	-65 to 150	°C
Power Dissipation	P <sub>D</sub>	1	W
DC Output Current	I <sub>OUT</sub>	50	mA
Soldering Temperature (under 10 sec)	T <sub>SOLDER</sub>	260	°C

\*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

**TRUTH TABLE**

MODE	CE#	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	H	X	X	High-Z	I <sub>SB1</sub>
Output Disable	L	H	H	High-Z	I <sub>CC</sub> , I <sub>CC1</sub>
Read	L	L	H	D <sub>OUT</sub>	I <sub>CC</sub> , I <sub>CC1</sub>
Write	L	X	L	D <sub>IN</sub>	I <sub>CC</sub> , I <sub>CC1</sub>

Note: H = V<sub>IH</sub>, L = V<sub>IL</sub>, X = Don't care.

**DC ELECTRICAL CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. <sup>3</sup>	MAX.	UNIT
Supply Voltage	V <sub>CC</sub>		2.7	3.0	5.5	V
Input High Voltage	V <sub>IH</sub> <sup>1</sup>		0.7* V <sub>CC</sub>	-	V <sub>CC</sub> +0.3	V
Input Low Voltage	V <sub>IL</sub> <sup>1</sup>		- 0.2	-	0.6	V
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> ≥ V <sub>IN</sub> ≥ V <sub>SS</sub>	- 1	-	1	μA
Output Leakage Current	I <sub>LO</sub>	V <sub>CC</sub> ≥ V <sub>OUT</sub> ≥ V <sub>SS</sub> , Output Disabled	- 1	-	1	μA
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -1mA	2.4	-	-	V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2mA	-	-	0.4	V
Average Operating Power supply Current	I <sub>CC</sub>	Cycle time = Min. CE# = 0.2V, I <sub>I/O</sub> = 0mA other pins at 0.2V or V <sub>CC</sub> - 0.2V	- 55	30	60	mA
	I <sub>CC1</sub>	Cycle time = 1μs CE# = 0.2V, I <sub>I/O</sub> = 0mA other pins at 0.2V or V <sub>CC</sub> - 0.2V	-	4	10	mA
Standby Power Supply Current	I <sub>SB1</sub>	CE# ≥ V <sub>CC</sub> - 0.2V	*C	4	50 <sup>4</sup>	μA
			*I	4	50 <sup>4</sup>	μA

Notes: 1. V<sub>IH</sub>(max) = V<sub>CC</sub> + 3.0V for pulse width less than 10ns. V<sub>IL</sub>(min) = V<sub>SS</sub> - 3.0V for pulse width less than 10ns.

2. Over/Undershoot specifications are characterized, not 100% tested.

3. Typical values are included for reference only and are not guaranteed or tested.

Typical values are measured at V<sub>CC</sub> = V<sub>CC</sub>(TYP.) and T<sub>A</sub> = 25°C

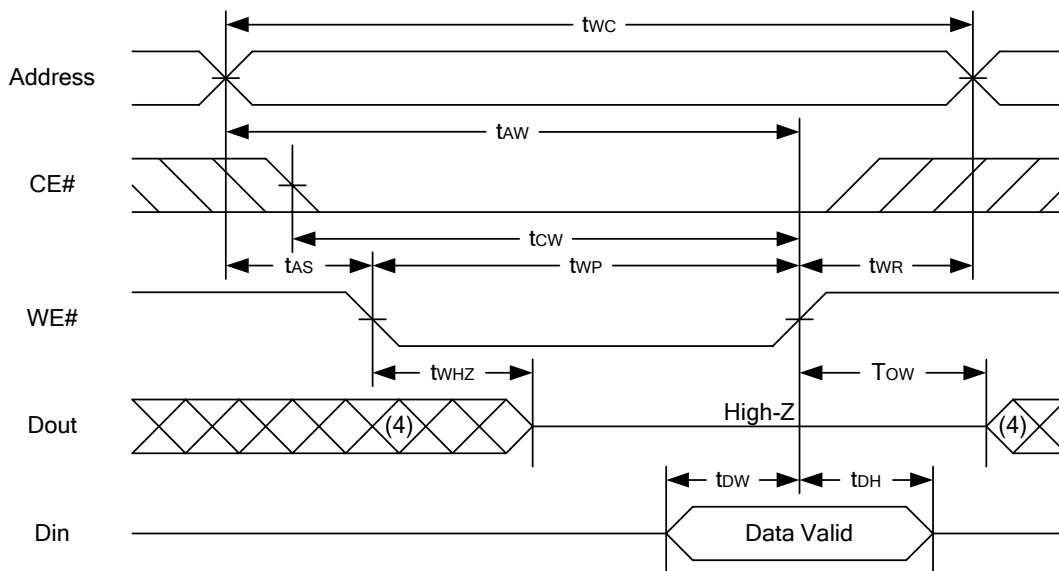
4. 25μA for special request

\*C=Commercial temperature/I = Industrial temperature

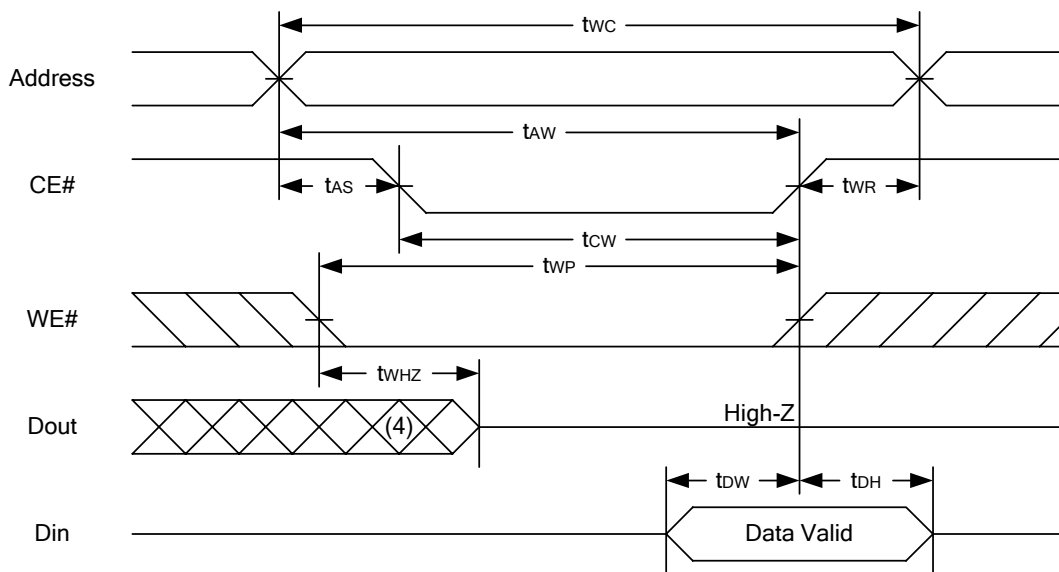


512K X 8 BIT LOW POWER CMOS SRAM

**WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)**



**WRITE CYCLE 2 (CE# Controlled) (1,2,5,6)**



Notes :

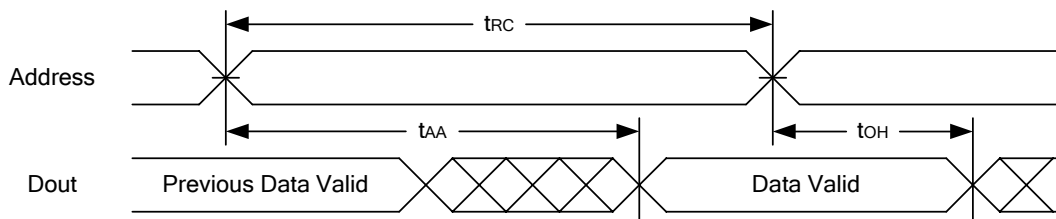
1. WE#, CE# must be high during all address transitions.
2. A write occurs during the overlap of a low CE#, low WE#.
3. During a WE# controlled write cycle with OE# low, t<sub>WP</sub> must be greater than t<sub>WHZ</sub> + t<sub>DW</sub> to allow the drivers to turn off and data to be placed on the bus.
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the CE# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
6. t<sub>OW</sub> and t<sub>WHZ</sub> are specified with C<sub>L</sub> = 5pF. Transition is measured ±500mV from steady state.



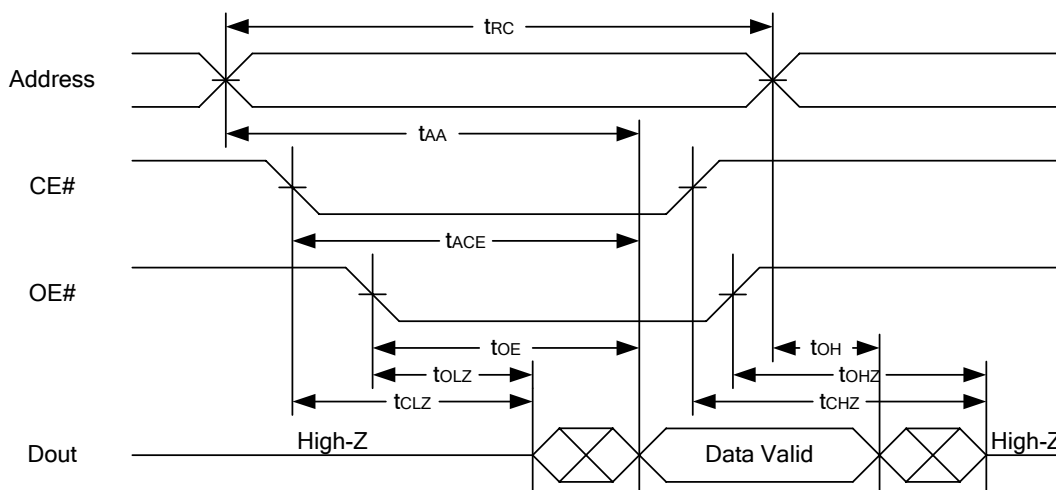
512K X 8 BIT LOW POWER CMOS SRAM

**TIMING WAVEFORMS**

**READ CYCLE 1 (Address Controlled) (1,2)**



**READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)**



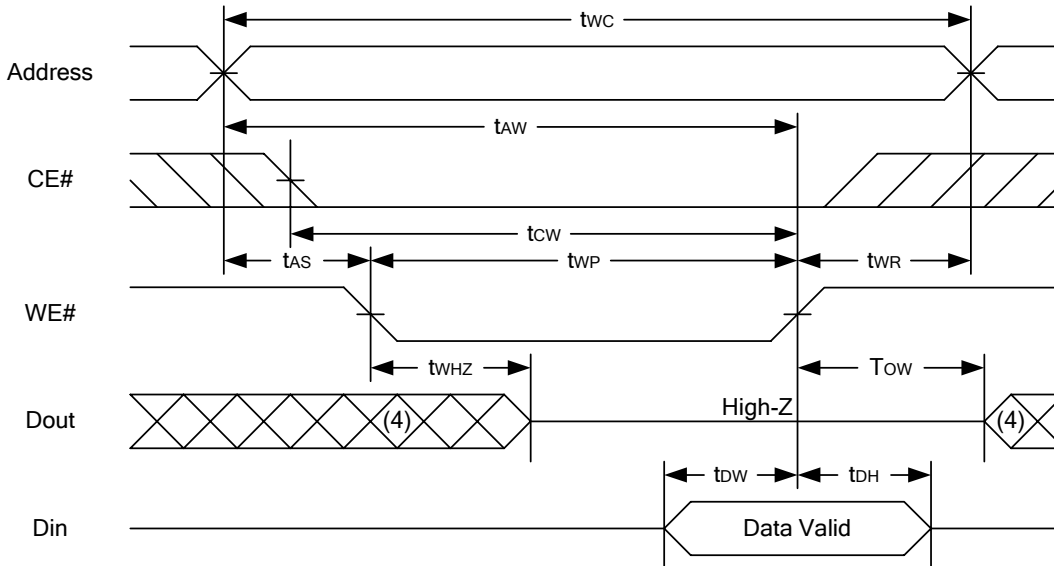
Notes :

1. WE# is high for read cycle.
2. Device is continuously selected OE# = low, CE# = low.
3. Address must be valid prior to or coincident with CE# = low,; otherwise  $t_{AA}$  is the limiting parameter.
4.  $t_{CLZ}$ ,  $t_{OLZ}$ ,  $t_{CHZ}$  and  $t_{OHZ}$  are specified with  $C_L = 5pF$ . Transition is measured  $\pm 500mV$  from steady state.
5. At any given temperature and voltage condition,  $t_{CHZ}$  is less than  $t_{CLZ}$ ,  $t_{OHZ}$  is less than  $t_{OLZ}$ .

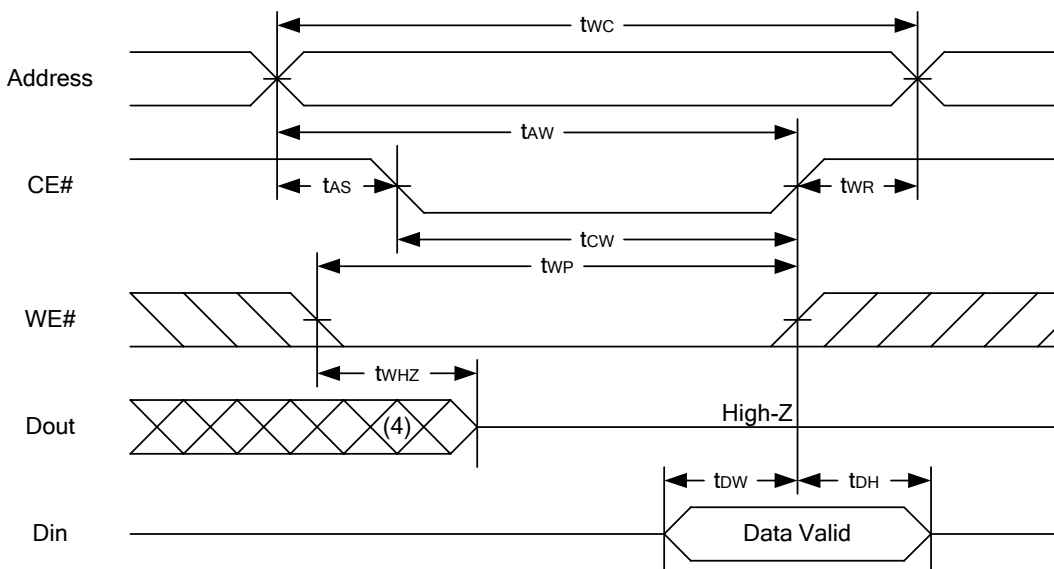


512K X 8 BIT LOW POWER CMOS SRAM

**WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)**



**WRITE CYCLE 2 (CE# Controlled) (1,2,5,6)**



Notes :

1. WE#, CE# must be high during all address transitions.
2. A write occurs during the overlap of a low CE#, low WE#.
3. During a WE# controlled write cycle with OE# low, twp must be greater than twhz + tdw to allow the drivers to turn off and data to be placed on the bus.
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the CE# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
6. tow and twhz are specified with CL = 5pF. Transition is measured ±500mV from steady state.

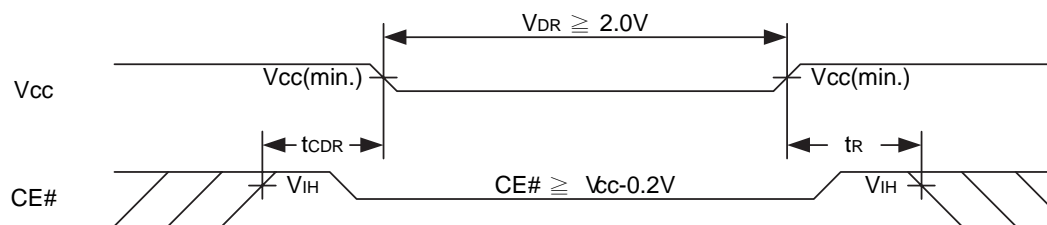


## 512K X 8 BIT LOW POWER CMOS SRAM

**DATA RETENTION CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V <sub>CC</sub> for Data Retention	V <sub>DR</sub>	CE# $\geq$ V <sub>CC</sub> - 0.2V	2.0	-	5.5	V
Data Retention Current	I <sub>DR</sub>	V <sub>CC</sub> = 2.0V CE# $\geq$ V <sub>CC</sub> - 0.2V	-	2	30	$\mu$ A
Chip Disable to Data Retention Time	t <sub>CDR</sub>	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t <sub>R</sub>		t <sub>RC</sub> *	-	-	ns

t<sub>RC</sub>\* = Read Cycle Time \*\*C=Commercial temperature/I=Industrial temperature

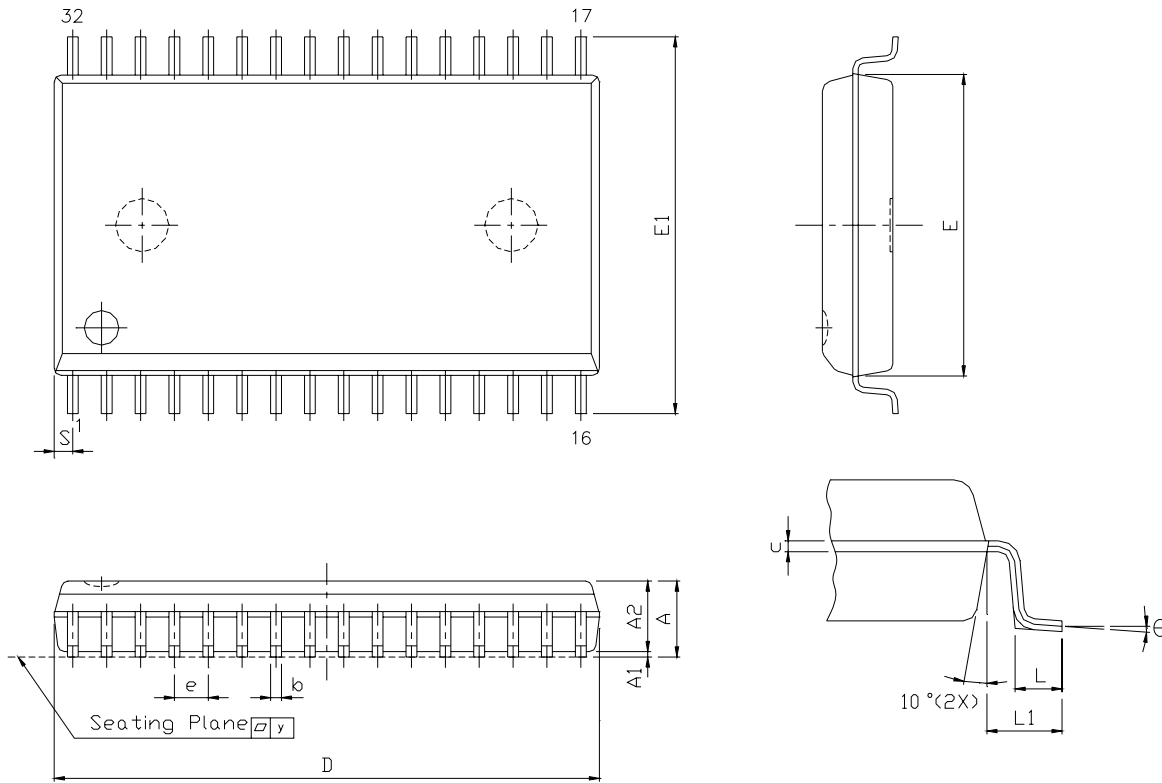
**DATA RETENTION WAVEFORM**



512K X 8 BIT LOW POWER CMOS SRAM

**PACKAGE OUTLINE DIMENSION**

**32 pin 450 mil SOP Package Outline Dimension**



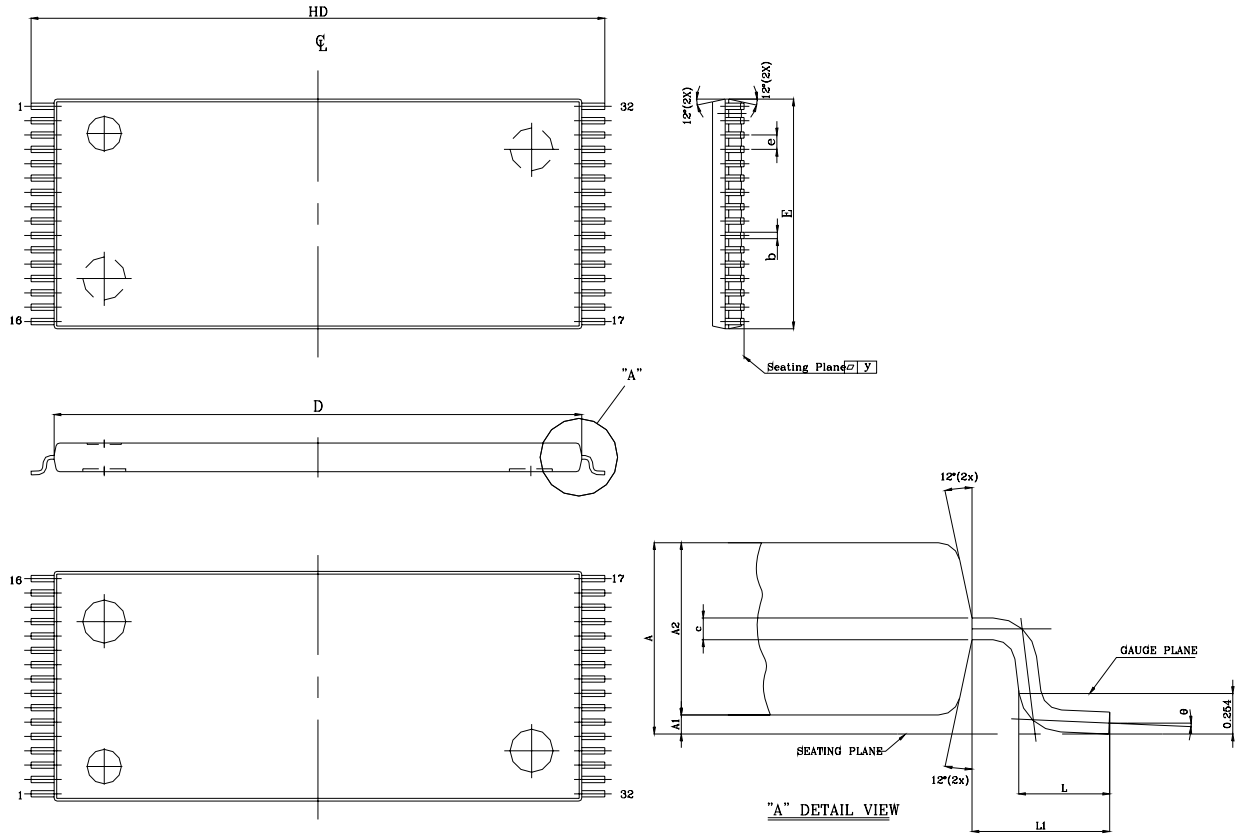
SYM.	UNIT	INCH.(BASE)	MM(REF)
A		0.118 (MAX)	2.997 (MAX)
A1		0.004(MIN)	0.102(MIN)
A2		0.111(MAX)	2.82(MAX)
b		0.016(TYP)	0.406(TYP)
c		0.008(TYP)	0.203(TYP)
D		0.817(MAX)	20.75(MAX)
E		0.445 ±0.005	11.303 ±0.127
E1		0.555 ±0.012	14.097 ±0.305
e		0.050(TYP)	1.270(TYP)
L		0.0347 ±0.008	0.881 ±0.203
L1		0.055 ±0.008	1.397 ±0.203
S		0.026(MAX)	0.660 (MAX)
y		0.004(MAX)	0.101(MAX)
θ		0° -10°	0° -10°





512K X 8 BIT LOW POWER CMOS SRAM

32 pin 8mm x 20mm TSOP-I Package Outline Dimension

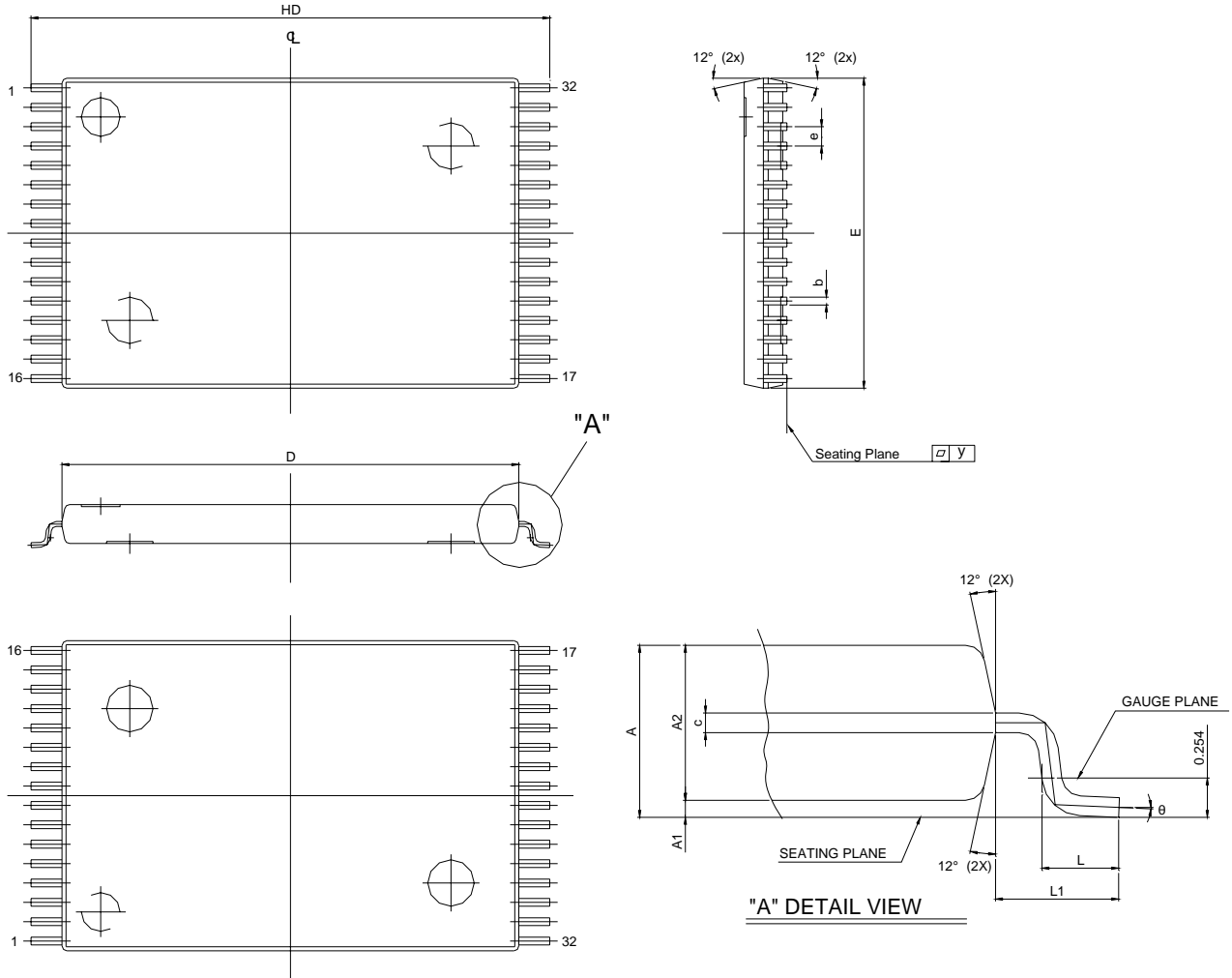


SYM.	UNIT	INCH(BASE)	MM(REF)
A		0.047 (MAX)	1.20 (MAX)
A1		0.004 ±0.002	0.10 ±0.05
A2		0.039 ±0.002	1.00 ±0.05
b		0.008 + 0.002 - 0.001	0.20 + 0.05 - 0.03
c		0.005 (TYP)	0.127 (TYP)
D		0.724 ±0.004	18.40 ±0.10
E		0.315 ±0.004	8.00 ±0.10
e		0.020 (TYP)	0.50 (TYP)
HD		0.787 ±0.008	20.00 ±0.20
L		0.0197 ±0.004	0.50 ±0.10
L1		0.0315 ±0.004	0.08 ±0.10
y		0.003 (MAX)	0.076 (MAX)
θ		0° ~ 5°	0° ~ 5°



512K X 8 BIT LOW POWER CMOS SRAM

32 pin 8mm x 13.4mm sTSSOP Package Outline Dimension



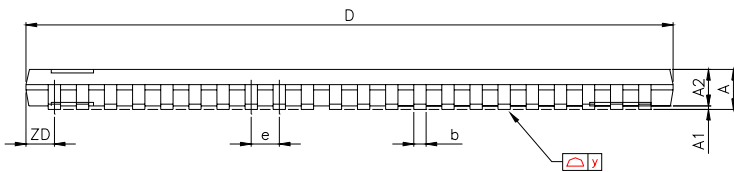
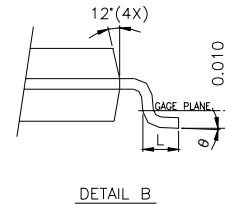
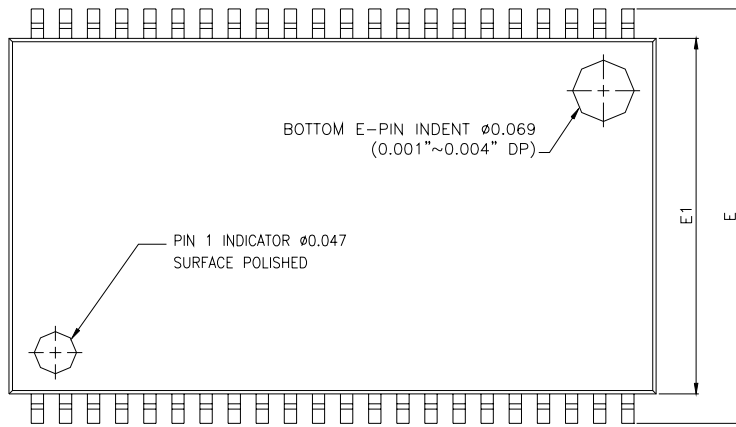
SYM.	UNIT	INCH(BASE)	MM(REF)
A		0.049 (MAX)	1.25 (MAX)
A1		0.005 ±0.002	0.130 ±0.05
A2		0.039 ±0.002	1.00 ±0.05
b		0.008 ±0.01	0.20±0.025
c		0.005 (TYP)	0.127 (TYP)
D		0.465 ±0.004	11.80 ±0.10
E		0.315 ±0.004	8.00 ±0.10
e		0.020 (TYP)	0.50 (TYP)
HD		0.528±0.008	13.40 ±0.20.
L		0.0197 ±0.004	0.50 ±0.10
L1		0.0315 ±0.004	0.8 ±0.10
y		0.003 (MAX)	0.076 (MAX)
Θ		0°~5°	0°~5°



512K X 8 BIT LOW POWER CMOS SRAM

PACKAGE DIMENSIONS

44-pin 400mil TSOP- II Package Outline Dimension

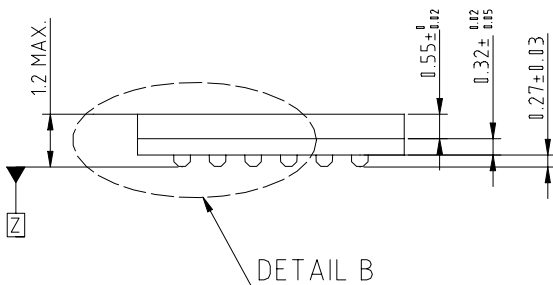
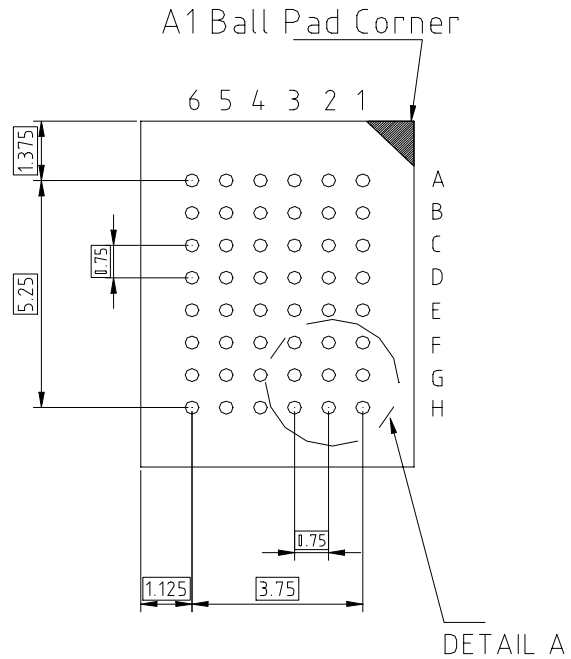
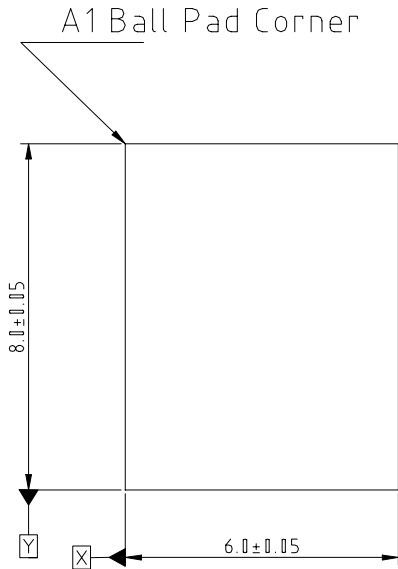


SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN MILS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	-	-	1.20	-	-	47.2
A1	0.05	0.10	0.15	2.0	3.9	5.9
A2	0.95	1.00	1.05	37.4	39.4	41.3
b	0.30	-	0.45	11.8	-	17.7
c	0.12	-	0.21	4.7	-	8.3
D	18.212	18.415	18.618	717	725	733
E	11.506	11.760	12.014	453	463	473
E1	9.957	10.160	10.363	392	400	408
e	-	0.800	-	-	31.5	-
L	0.40	0.50	0.60	15.7	19.7	23.6
ZD	-	0.805	-	-	31.7	-
y	-	-	0.076	-	-	3
$\theta$	0°	3°	6°	0°	3°	6°

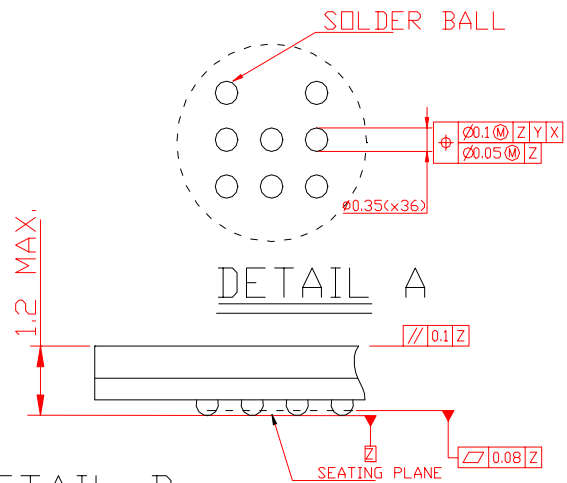


512K X 8 BIT LOW POWER CMOS SRAM

36 ball 6mm x 8mm TFBGA Package Outline Dimension



SIDE VIEW

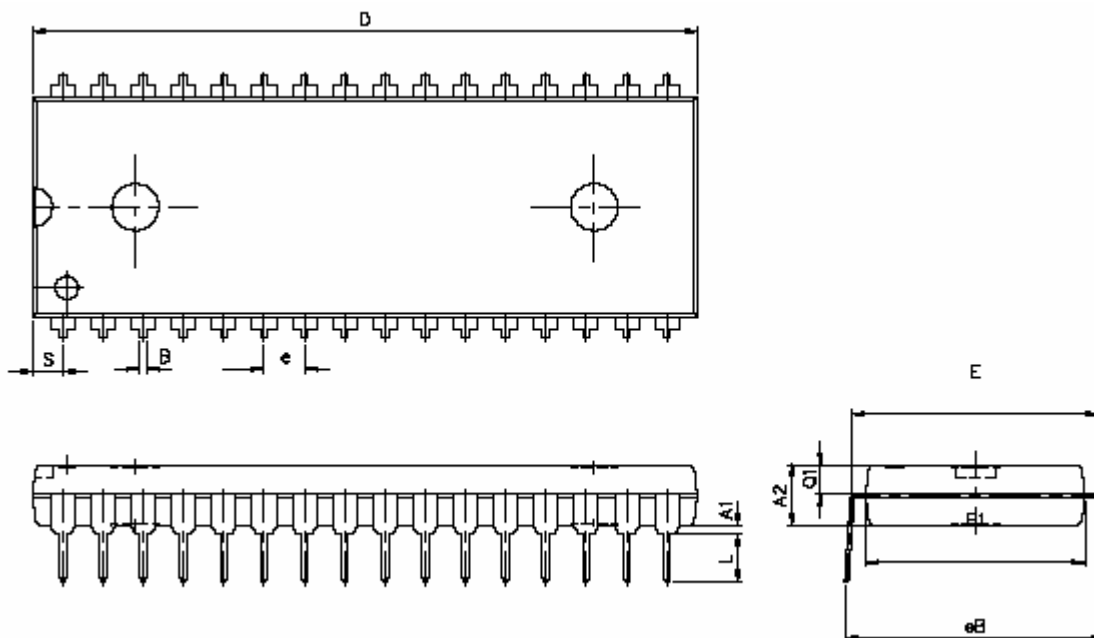


DETAIL B



512K X 8 BIT LOW POWER CMOS SRAM

32 pin 600 mil P-DIP Package Outline Dimension



SYM. \ UNIT	INCH(BASE)	MM(REF)
A1	0.001 (MIN)	0.254 (MIN)
A2	0.150 ± 0.005	3.810 ± 0.127
B	0.018 ± 0.005	0.457 ± 0.127
D	1.650 ± 0.005	41.910 ± 0.127
E	0.600 ± 0.010	15.240 ± 0.254
E1	0.544 ± 0.004	13.818 ± 0.102
e	0.100 (TYP)	2.540 (TYP)
eB	0.640 ± 0.020	16.256 ± 0.508.
L	0.130 ± 0.010	3.302 ± 0.254
S	0.075 ± 0.010	1.905 ± 0.254
Q1	0.070 ± 0.005	1.778 ± 0.127

Note : D/E1/S dimension do not include mold flash.



## 512K X 8 BIT LOW POWER CMOS SRAM

**ORDERING INFORMATION**

## Ordering Codes

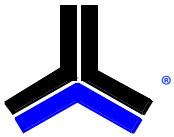
Alliance	Organization	VCC range	Package	Operating Temp	Speed ns
<b>AS6C4008-55PCN</b>	512k x 8	2.7-5.5V	32pin 600mil PDIP	Commercial ~ 0° C to 70° C	55
<b>AS6C4008-55SIN</b>	512k x 8	2.7-5.5V	32pin 450mil SOP	Industrial ~ -40° C to 85° C	55
<b>AS6C4008-55TIN</b>	512k x 8	2.7-5.5V	32pin TSOP-I (8 x 20 mm)	Industrial ~ -40° C to 85° C	55
<b>AS6C4008-55STIN</b>	512k x 8	2.7-5.5V	32pin sTSOP (8 x 13.4 mm)	Industrial ~ -40° C to 85° C	55
<b>AS6C4008-55ZIN</b>	512k x 8	2.7-5.5V	32pin TSOP-II 400mil *	Industrial ~ -40° C to 85° C	55
<b>AS6C4008-55BIN</b>	512k x 8	2.7-5.5V	36pin TFBGA (6mm x 8mm)*	Industrial ~ -40° C to 85° C	55

\*Coming Soon!

## Part numbering system

AS6C	4008	- 55	X	X	N
low power SRAM prefix	Device Number 40 = 4M 08 = by 8	Access Time	Package Options: P = 32 pin 600 mil P-DIP S = 32 pin 450 mil SOP T = 32 pin TSOP-I (8mm x 20 mm) ST = 32 pin sTSOP (8mm x 13.4 mm) Z = 44 pin TSOP-II 400 mil * B = 36 pin TFBGA (6mm x 8mm)*	Temperature Range: C = Commercial (0° C to +70° C) I = Industrial (-40° to +85° C)	N = Lead Free ROHS Compliant Part

\* Coming Soon!



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Fax: 650-525-0449

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Part Number: AS6C4008

Document Version: v. 1.0

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